## **CHEMTRONICS® Technical Data Sheet**

## TDS # CW8

# Chemask<sup>®</sup> W

## **PRODUCT DESCRIPTION**

Chemask<sup>®</sup> W solder mask is water soluble and designed to be removed with most aqueous cleaning systems. Chemask<sup>®</sup> W contains high temperature compounds that protect component-free areas from solder during wave soldering. This water soluble formulation is stable to rosin, organic and inorganic fluxes.

- Protects boards from molten solder to 515°F (268°C)
- Compatible with most flux types
- Leaves no corrosive residue
- Non-contaminating
- UV Detectable

## **TYPICAL APPLICATIONS**

During wave soldering, Chemask<sup>®</sup> W protects:

- Component Free Areas
- Gold Connectors
- Gold Fingers
- Pin Connectors

## TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Base Material	Synthetic Resin		
Color	Blue		
Solvent Stability	Dissolves in water with or without detergent		
Flux Compatibility	Aqueous Flux		
Temperature Stability	515°F (268°C)		
Tack-Free Drying Time (10 mils @ 77°F)	20 min.		
Cure Time (10 mils @ 77°F)	1 hr.		
Viscosity (@ 77°F) (± 300 cps)	15,000 cps		
Viscosity Adjusted With	n DI Water		
<b>Contains UV Indicator</b>	Yes		
Solids Content	~ 40%		
Flash Point	Nonflammable		
Weight/Gallon	8.8 lbs.		
Shelflife	1 year		

## COMPATIBILITY

Chemask<sup>®</sup> W is generally compatible with most materials used in printed circuit board fabrication. As with any solder masking agent, compatibility with substrate must be determined on a non-critical area prior to use.

#### **APPLICATION METHOD**

Squeeze Bottle/Syringe	Yes
Spatula	Yes
Screening	Yes
Stencil	Yes
Automatic Dispensing	Yes

## **USAGE INSTRUCTIONS**

For industrial use only.

Read MSDS carefully prior to use.

Chemask<sup>®</sup> W solder masking agent is engineered for all electronic manufacturing applications. When applying by hand using squeeze bottle or spatula, insure that all areas of the pre-tinned hole are evenly covered on the side to be soldered. For screening applications, properly clean and prepare screen, then apply masking agent in the same manner as solder paste. Automatic dispensing equipment may also be used as appropriate.

**REMOVAL:** After allowing the mask to become fully cured, the mask may be washed away with water. For optimum performance, water soluble mask may be removed with agitation, ultrasonic, or industrial washing. Surfactants may be added to increase cleaning efficiency.

#### AVAILABILITY

CW88 oz. Squeeze BottleCW11 Gal. Liquid

## TECHNICAL & APPLICATION ASSISTANCE

Chemtronics<sup>®</sup> provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.** 

## ENVIRONMENTAL IMPACT DATA

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CFC	0.0%	VOC	5.0%	
HCFC	0.0%	HFC	0.0%	
Cl. Solv.	0.0%	ODP	0.00	

CFC, HCFC, CL. SOLV., VOC, and HFC numbers shown are the content by weight. Ozone depletion potential (ODP) is determined in accordance with the Montreal Protocol and U.S. Clean Air Act of 1990. The ODP of this product is 0.0. It is the sum of the ODP of the substances that may contribute to the depletion of stratospheric ozone, based upon the weight of each substance in the product's formulation.

#### NOTE:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS<sup>®</sup> does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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